

VERSION WITH MARKINGS TO SHOW CHANGES**In The Claims**

19.(amended three times) A semiconductor chip package, comprising:
a semiconductor chip;
conductive leads electrically connected to and extending over a surface of the chip;
a continuous body of encapsulating material covering at least a portion of the chip [and fully encapsulating the conductive leads]; [and]
electrodes each having a first portion disposed in the encapsulating material and contacting a conductive lead and a second portion protruding from the encapsulating material; and
the body of encapsulating material fully encapsulating the conductive leads except for the immediate point of contact with the electrodes where the encapsulating material is necessarily displaced to allow the electrode to contact the lead.